

**Amendments to the Specification:**

Please replace paragraph 13, on page 5, with the following amended paragraph:

--Other exemplary microwave modules are disclosed in U.S. Pat. No. 6,255,730 of Dove, et al. entitled "Integrated Low Cost Thick Film RF Module", and in the United States patent application Pat. No. 6,953,698 of Casey, et al. entitled "Methods for Making Microwave Circuits" (~~Ser. No. 10/600,143 filed Jun. 19, 2003~~), both of which are hereby incorporated by reference.--

Please replace paragraph 15, on page 6, with the following amended paragraph:

-- As shown in either FIG. 1 or FIG. 2, reference numerals in the one-hundred range shown in FIG. 1 and reference numerals in the two-hundred range shown in FIG. 2, FIGS. 1 & 2, each of the microwave modules 100, 200 may be cut between a respective first position (116 or 216) and a respective second position (118 or 218), thereby creating a cut edge for each module. The first position 116, 216 is chosen to provide a minimum reveal of the end 110, 214 of the conductor 102, 208. As defined herein, a "minimum reveal" is the minimum amount of conductor reveal required for bonding another conductor thereto, as determined by necessary manufacturing variations. The second position 118, 218 is chosen to be at or near the end 110, 214 of the conductor 102, 208 so that the conductor terminates at or near the cut edge. It is preferable, however, that the conductor terminate "at" the cut edge. Although the cuts 116, 216, 118, 218 are shown to be square with existing edges of the microwave modules 100, 200, they need not be. By way of example, the edges may be cut by means of a laser or saw.--

Please replace paragraph 17, on page 6, with the following amended paragraph:

-- If desired, and as described hereinabove, reference numerals in the one-hundred range are shown in FIG. 1 and reference numerals in the two-hundred range are shown in FIG. 2, the ends 110, 214 of conductors 102, 208 may be sized

wider to provide a greater bonding surface for conductor-to-conductor joining, as will be described in greater detail below.--

Please replace paragraphs 21 and 22, on pages 7 and 8, with the following amended paragraphs:

--FIG. 4 illustrates a method 400 for cutting and coupling first and second microwave modules (which may be of the types shown in FIG. 1 and/or FIG. 2). The method comprises, for each of the microwave modules, ~~cutting~~ cut 402 the microwave module in proximity to a first end of one of its conductors, thereby defining a first edge of the microwave module. ~~Then, mount 404 the~~ The microwave modules are then mounted 404 adjacent one another, with their first edges facing each other. Thereafter, electrically couple 406 the first ends of the conductors are ~~electrically coupled 406~~ to one another. Finally, place 408 a ground shield cap is ~~placed 408~~ over the conductor coupling, and ~~the ground shield cap is electrically coupled~~ couple the ground shield cap to ground shields of each of the microwave modules.

FIG. 5 illustrates a method 500 for assembling a microwave circuit from first and second microwave modules such as those shown in FIG. 1 and/or FIG. 2. First, select 502 the microwave modules ~~are selected 502~~ and ~~mounted~~ mount 504 the modules adjacent one another, with cut edges of each module facing one another. ~~Ends~~ Electrically couple 506 ends of the conductors of the microwave modules ~~are then electrically coupled 506~~ to one another. Finally, place 508 a ground shield cap ~~is placed 508~~ over the conductor coupling, and the ground shield cap is electrically coupled to the ground shields of each of the microwave modules.--